



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20251217000.2

Qualification of RFAB using qualified Process Technology, Datasheet, Die Revision, additional Assembly site and options for select devices

Change Notification / Sample Request

Date: December 17, 2025

To: Mouser PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments (TI). The details of this change are on the following pages, and are in alignment with our standard product change notification (PCN) [process](#).

TI requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification, given that samples are not built ahead of the change.

The Proposed First Ship date in this PCN letter is the earliest possible date that customers could receive the changed material. It is our commitment that the changed device will not ship before that date. If samples are requested within the 60 day sample request window, customers will still have 30-days to complete their evaluation regardless of the proposed 1st ship date.

As referenced in the "reason for change" below, this particular PCN relates to TI's multiyear transition, announced in 2020, to close our 150mm production and move more capacity into 300mm. We are entering the final phases of this transition, and the final 150mm wafers started in October 2025. **Thus, it's critical that you take the appropriate actions, noted in this PCN, to prepare for applicable product changes.**

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the Change Management team. For sample requests or sample related questions, contact your local Field Sales Representative. As always, we thank you for your continued business.

Change Management Team
SC Business Services

20251217000.2**Attachment: 1****Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TPS76301QDBVRG4Q1	NULL
TPS76333QDBVRQ1	NULL
TPS76350QDBVRQ1	NULL
TPS76301QDBVRQ1	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20251217000.2	PCN Date:	December 17, 2025
Title:	Qualification of RFAB using qualified Process Technology, Datasheet, Die Revision, additional Assembly site and options for select devices		
Customer Contact:	Change Management Team	Dept:	Quality Services
Proposed 1st Ship Date:	June 15, 2026	Sample requests accepted until:	February 15, 2026*
*Sample requests received after February 15, 2026 will not be supported.			
Change Type:			
<input checked="" type="checkbox"/> Assembly Site	<input checked="" type="checkbox"/> Design	<input type="checkbox"/>	Wafer Bump Material
<input checked="" type="checkbox"/> Assembly Process	<input checked="" type="checkbox"/> Data Sheet	<input type="checkbox"/>	Wafer Bump Process
<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Part number change	<input checked="" type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/> Mechanical Specification	<input checked="" type="checkbox"/> Test Site	<input checked="" type="checkbox"/>	Wafer Fab Material
<input checked="" type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process	<input checked="" type="checkbox"/>	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the addition of RFAB using the LBC7 qualified process technology and additional Assembly site for the devices listed below.

Current Fab Site		Additional Fab Site			
Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter
DFAB	LBC3S	150 mm	RFAB	LBC7	300 mm

The die was also changed as a result of the process change.

Construction differences are as follows:

	Current	Additional
Assembly/Test Site	LEN	PHI
Wire diam/type	Au; 1.0 mil	Cu; 1.0 mil
Mount compound	SID#0003C10332	8095733
Mold compound	SID#0011G60007	4222198
Final Wafer Thickness	254um	152um
Marking Appearance	Stripe	Dot

The product datasheet(s) is updated as seen in the change revision history below:



TPS763-Q1
SGLS247C – SEPTEMBER 2011 – REVISED DECEMBER 2025

Changes from Revision B (March 2016) to Revision C (December 2025)		Page
• Updated the numbering format for tables, figures, and cross-references throughout the document.....	1	
• Added new chip information throughout the document.....	1	
• Updated title from: TPS763xx-Q1 Low-Power, 150-mA, Low-Dropout Linear Regulators to: TPS763-Q1 Automotive 150mA, 10V, Low-Dropout Linear Regulator.....	1	
• Updated temperature Grade 1 maximum from +125°C to +150°C in Features section.....	1	
• Updated output voltage.....	1	
• Deleted low-dropout regulator data.....	1	
• Added device CDM ESD classification: level C4 (new chip), input voltage range, fixed and adjustable input voltage range, output current, output voltage accuracy, low quiescent current, new chip dropout voltage, supported ESR range, active over-shoot pulldown protection, new chip operating junction temperature, and °C/W packaging data.....	1	
• Updated applications section.....	1	
• Updated description section.....	1	
• Deleted Voltage Options section.....	3	
• Added nominal output capacitance note.....	3	
• Updated Pin Configuration and Functions section.....	3	
• Added new chip typical characteristics.....	9	
• Updated overview section.....	16	
• Added fixed and adjustable new chip functional block diagrams.....	16	
• Deleted Regulator Protection section.....	17	
• Added Output Enable section.....	17	
• Added Dropout Voltage section.....	18	
• Added Current Limit section.....	18	
• Added Output Pulldown section.....	19	
• Added Thermal Shutdown section.....	19	
• Added Device Functional Mode Comparison section.....	19	
• Updated Device Functional Mode Comparison table.....	19	
• Moved Device Functional Mode Comparison table to Device Functional Mode Comparison section.....	19	
• Updated Normal Operation section.....	20	
• Added steady dropout state to Dropout Operation section.....	20	
• Updated Disabled section.....	20	
• Added Adjustable Device Feedback Resistors section.....	21	
• Added Recommended Capacitor Types sections.....	21	
• Moved External Capacitor Requirements information to Recommended Capacitor Types.....	21	
• Added Reverse Current section.....	25	
• Added Feed-Forward Capacitor (CFF) section.....	25	
• Added Power Dissipation (PD) section.....	26	
• Moved Power Dissipation and Junction Temperature information to Added Power Dissipation (PD) section.....	26	
• Added Estimating Junction Temperature section.....	26	
• Deleted External Capacitor Requirements section.....	27	
• Updated Output Voltage Programming section.....	27	
• Added new chip figures to Application Curves section.....	28	

Product Folder	Current Datasheet Number	New Datasheet Number	Link to full datasheet
TPS763-Q1	SGLS247B	SGLS247C	http://www.ti.com/product/TPS763-Q1

Qual details are provided in the Qual Data Section.

Reason for Change:

These changes are part of our multiyear plan to transition products from our 150-millimeter factories to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

Any differences/changes between the LBC3S die and LBC7 die have been made in the data sheet using "Legacy chip" (LBC3S) and "New chip" (LBC7). See standard data packet.

Impact on Environmental Ratings:

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS

REACH

Green Status

IEC 62474

<input checked="" type="checkbox"/> No Change			
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Changes to product identification resulting from this PCN:

Fab Site

Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
DFAB	DLN	USA	Dallas
RFAB	RFB	USA	Richardson

Die Rev:

Current

New

Die Rev [2P]	Die Rev [2P]
B	A

Assembly Site

Information:

Assembly Site	Assembly Site Origin Code (22L)	Assembly Site Country Code (23L)	Assembly Site City
LEN	LIN	TWN	Taichung
PHI	PHI	PHL	Baguio City

Sample product shipping label (not actual product label):



Product Affected

TPS76301QDBVRG 4Q1	TPS76333QDBVRG4 Q1	TPS76350QDBVRG 4Q1	TPS76350QDBVR Q1
TPS76301QDBVRQ 1	TPS76333QDBVRQ 1		

Product Attributes

Attributes		Qual Device: TPS76301QDBVRM3Q1		Qual Device: TPS76333QDBVRM3Q1		Qual Device: TPS76350QDBVRM3Q1		QBS Package Reference: TLV2401QDBVRQ1		QBS Process Reference: SN3257QDYYRQ1		QBS Package Reference: TPS3820-50QDBVRQ1		QBS Product Reference: TPS76950QDBVRG4MQ1	
Automotive Grade Level	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1
Operating Temp Range (C)	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125
Product Function	Power Management	Power Management	Power Management	Power Management	Power Management	Signal Chain	Signal Chain	Logic, Signal Chain	Logic, Signal Chain	Power Management	Power Management	Power Management	Power Management	Power Management	Power Management
Wafer Fab Supplier	RFAB	RFAB	RFAB	RFAB	RFAB	DL-LIN	DL-LIN	RFAB	DL-LIN	DL-LIN	RFAB	DL-LIN	RFAB	DL-LIN	RFAB
Assembly Site	PHI	PHI	PHI	PHI	PHI	PHI	PHI	PHI	PHI	PHI	PHI	PHI	PHI	PHI	PHI
Package Group	SOT	SOT	SOT	SOT	SOT	SOT	SOT	SOT	SOT	SOT	SOT	SOT	SOT	SOT	SOT
Package Designator	DBV	DBV	DBV	DBV	DBV	DBV	DBV	DBV	DBV	DBV	DBV	DBV	DBV	DBV	DBV
Pin Count	5	5	5	5	5	5	5	16	16	5	5	5	5	5	5

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device [TPS76301QDBVRM3Q1](#) is qualified at MSL1 260C
- Qual Device [TPS76333QDBVRM3Q1](#) is qualified at MSL1 260C
- Qual Device [TPS76350QDBVRM3Q1](#) is qualified at MSL1 260C
- Qual Device [TPS76350QDBVRM3Q1](#) is qualified at MSL1 260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: TPS76301QDBVRM3Q1	Qual Device: TPS76333QDBVRM3Q1	Qual Device: TPS76350QDBVRM3Q1	QBS Package Reference: TLV2401QDBVRQ1	QBS Process Reference: SN3257QDYYRQ1	QBS Package Reference: TPS3820-50QDBVRQ1	QBS Product Reference: TPS76950QDBVRG4MQ1	
Test Group A - Accelerated Environment Stress Tests															
PC	A1	JEDEC J-STD-020 JEDEC-A113	3	77	Preconditioning	MSL1 260C	-	1/All/0	-	-	-	-	-	3/All/0	1/All/0
HAST	A2	JEDEC JESD22-A110	3	77	Biased HAST	130C/85%RH	96 Hours	1/77/0	-	-	-	-	-	3/244/2	1/77/0
Test Group B - Accelerated Lifetime Simulation Tests															
AC/UHAST	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Autoclave	121C/15psig	96 Hours	-	-	-	-	-	-	3/231/0	-
AC/UHAST	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Unbiased HAST	130C/85%RH	96 Hours	1/77/0	-	-	-	-	-	-	1/77/0
TC	A4	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle	-65C/150C	500 Cycles	1/77/0	-	-	-	-	-	3/231/0	1/77/0
TC-BP	A4	MIL-STD883 Method 2011	1	5	Post Temp Cycle Bond Pull	-	-	1/5/0	-	-	-	-	-	-	1/5/0
HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	150C	1000 Hours	1/45/0	-	-	-	-	-	-	1/45/0
HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	175C	500 Hours	-	-	-	-	-	-	3/135/0	-
Test Group C - Package Assembly Integrity Tests															
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	-	-	3/15/0	3/90/0	-	1/30/0	
WBP	C2	MIL-STD883 Method 2011	1	30	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	-	-	3/15/0	3/90/0	-	1/30/0	
SD	C3	JEDEC J-STD-002	1	15	PB Solderability	>95% Lead Coverage	-	-	-	-	1/15/0	1/15/0	-	-	
SD	C3	JEDEC J-STD-002	1	15	PB-Free Solderability	>95% Lead Coverage	-	-	-	-	1/15/0	1/15/0	-	-	
PD	C4	JEDEC JESD22-B100 and B108	3	10	Physical Dimensions	Cpk>1.67	-	1/10/0	-	-	3/30/0	3/30/0	-	1/10/0	
Test Group D - Die Fabrication Reliability Tests															
EM	D1	JESD61	-	-	Electromigration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements			
TDDB	D2	JESD35	-	-	Time Dependent Dielectric Breakdown	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements			

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: TPS76301QDBVRM3Q1	Qual Device: TPS76333QDBVRM3Q1	Qual Device: TPS76356QDBVRM3Q1	QBS Package Reference: TLV2401QDBVRQ1	QBS Process Reference: SN3257QDYYRQ1	QBS Package Reference: TPS3820-5Q0QDBVRQ1	QBS Product Reference: TPS76256QDBVRG4M01	
HCI	D3	JESD60 & 28	-	-	Hot Carrier Injection	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements				
BTI	D4	-	-	-	Bias Temperature Instability	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements				
SM	D5	-	-	-	Stress Migration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements				
Test Group E - Electrical Verification Tests															
ESD	E2	AEC Q100-002	1	3	ESD HBM	-	2000 Volts	-	-	-	1/3/0	-	-	-	
ESD	E3	AEC Q100-011	1	3	ESD CDM	-	500 Volts	-	-	-	1/3/0	-	-	-	
LU	E4	AEC Q100-004	1	3	Latch-Up	Per AEC Q100-004	-	-	-	-	1/3/0	-	-	-	
ED	E5	AEC Q100-009	3	30	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	1/30/0	-	-	-	3/90/0	3/90/0	-	1/3/0
Additional Tests															

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/800 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Ambient Operating Temperature by Automotive Grade Level:

- Grade 0 (or E): -40C to +150C
- Grade 1 (or Q): -40C to +125C
- Grade 2 (or T): -40C to +105C
- Grade 3 (or I) : -40C to +85C

E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):

- Room/Hot/Cold : HTOL, ED
- Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU
- Room : AEC/HAST

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-NPD-2505-056

ZVEI ID: SEM-DE-03, SEM-DS-01, SEM-DS-02, SEM-PW-02, SEM-PW-09, SEM-PW-13, SEM-PA-02, SEM-PA-03, SEM-PA-07, SEM-PA-08, SEM-PA-11, SEM-PA-14, SEM-PA-18, SEM-QG-01

For alternate parts with similar or improved performance, please visit the product page on TI.com

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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